



SOD141

Hermetically sealed plastic package; axial leaded; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	A (axial)
Package type descriptive code	DO-201AD
Package type industry code	DO-201AD
Package style descriptive code	ALF (axial (leaded) long form)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	DO-201AD
Mounting method type	T (through-hole mount)
Issue date	18-5-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.2	-	8.4	9.6	mm
ΦD	package diameter		4.8	-	5.1	5.3	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

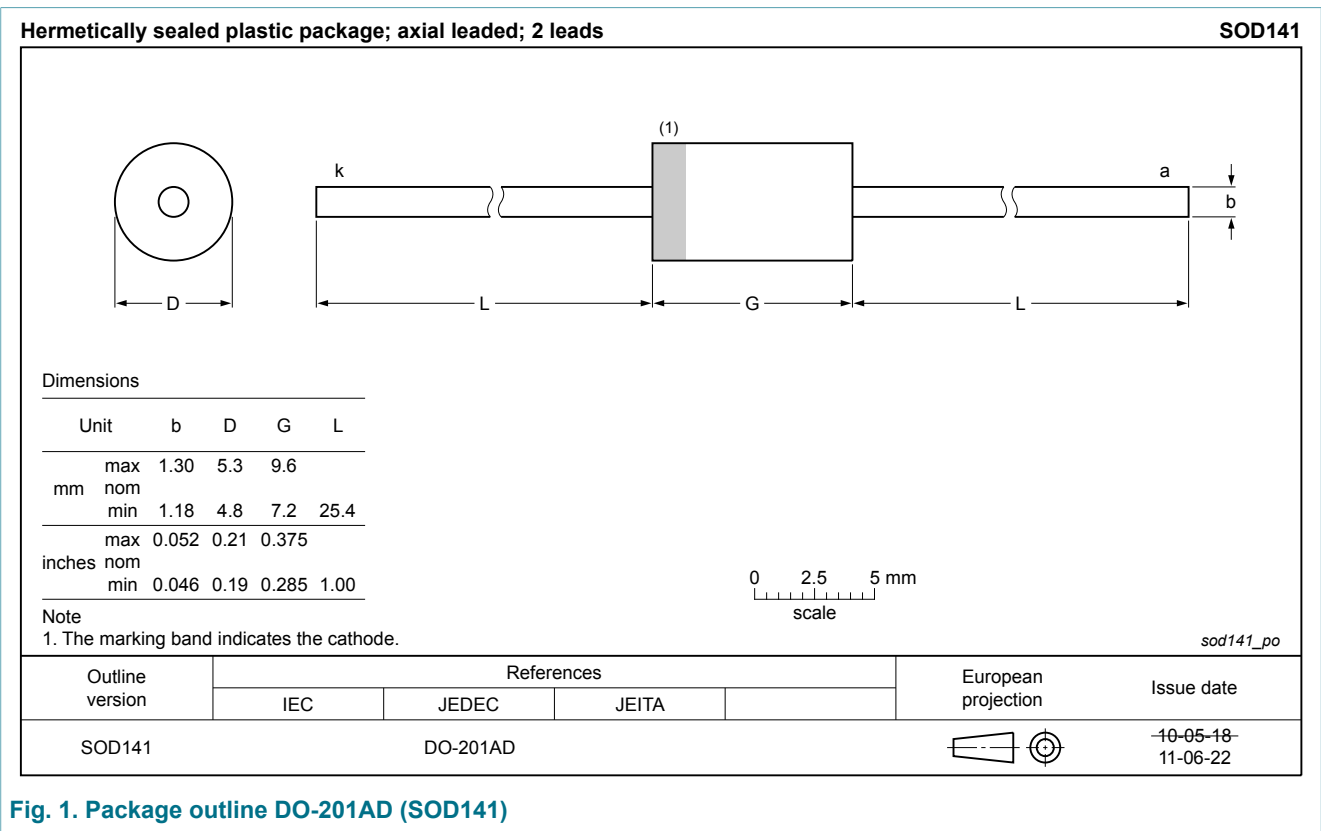


Fig. 1. Package outline DO-201AD (SOD141)

3. Legal information

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